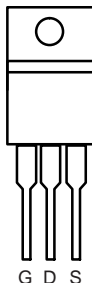


N-Channel 200-V (D-S) MOSFET

PRODUCT SUMMARY

$V_{(BR)DSS}$ (V)	$r_{DS(on)}$ (Ω)	I_D (A)
200	0.122 at $V_{GS} = 10$ V	25

TO-220AB



Top View



N-Channel MOSFET

FEATURES

- DT-Trench Power MOSFET
- 175 °C Junction Temperature
- Low Thermal Resistance Package
- 100 % R_g and UIS tested

APPLICATIONS

- LCD/LED TV
- Consumer Appliances
- Lighting
- AC-DC Power Supply


RoHS*
 COMPLIANT

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	200	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current	V_{GS} at 10 V	$T_C = 25$ °C	A
		$T_C = 100$ °C	
Pulsed Drain Current	I_{DM}	100	A
Single Pulse Avalanche Energy	E_{AS}	365	
Avalanche Current	I_{AR}	25	A
Repetitive Avalanche Energy	E_{AR}	14	mJ
Maximum Power Dissipation	P_D	$T_C = 25$ °C	W
		$T_A = 25$ °C ^b	
Peak Diode Recovery dV/dt	dV/dt	5.0	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 175	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300	

THERMAL RESISTANCE RATINGS

PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient (PCB Mounted, Steady-State)	R_{thJA}	-	65	°C/W
Maximum Junction-to-Case (Drain)	R_{thJC}	-	4.98	

a. Package limited.

b. When Mounted on 1" square PCB (FR-4 material).

c. See SOA curve for voltage derating.

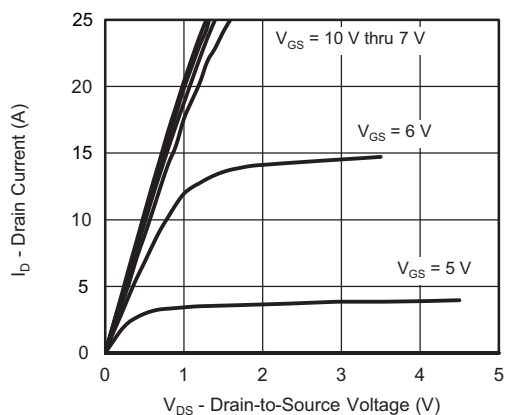
SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA	200	-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2	-	4	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 160 V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 160 V, V _{GS} = 0 V, T _J = 125 °C	-	-	100	
		V _{DS} = 160 V, V _{GS} = 0 V, T _J = 175 °C	-	-	2	mA
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 10 V, V _{GS} = 10 V	25	-	-	A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = 10 V, I _D = 10 A	-	0.122	0.145	Ω
		V _{GS} = 7.5 V, I _D = 8 A	-	0.135	0.158	
Forward Transconductance ^a	g _{fs}	V _{DS} = 20 V, I _D = 10 A	-	15	-	S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 160 V, f = 1 MHz	-	2450	-	pF
Output Capacitance	C _{oss}		-	350	-	
Reverse Transfer Capacitance	C _{rss}		-	90	-	
Total Gate Charge ^c	Q _g	V _{DS} = 160 V, V _{GS} = 10 V, I _D = 10 A	-	25	41	nC
Gate-Source Charge ^c	Q _{gs}		-	4.5	-	
Gate-Drain Charge ^c	Q _{gd}		-	13	-	
Gate Resistance	R _g	f = 1 MHz	-	3.9	-	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 160 V, R _L = 1.67 Ω I _D ≅ 10 A, V _{GEN} = 10 V, R _g = 1 Ω	-	15	26	ns
Rise Time ^c	t _r		-	25	44	
Turn-Off Delay Time ^c	t _{d(off)}		-	27	54	
Fall Time ^c	t _f		-	9	20	
Drain-Source Body Diode Ratings and Characteristics ^b (T _C = 25 °C)						
Pulsed Current (t = 100 μs)	I _{SM}		-	-	100	A
Forward Voltage ^a	V _{SD}	I _F = 20 A, V _{GS} = 0 V		0.75	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 20 A, d /dt = 100 A/μs	-	88	176	ns
Peak Reverse Recovery Charge	I _{RM(REC)}		-	5	10	A
Reverse Recovery Charge	Q _{rr}			0.22	0.44	μC

Notes

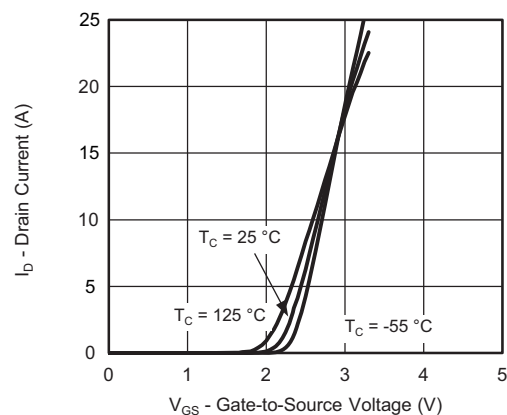
- Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.
- Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

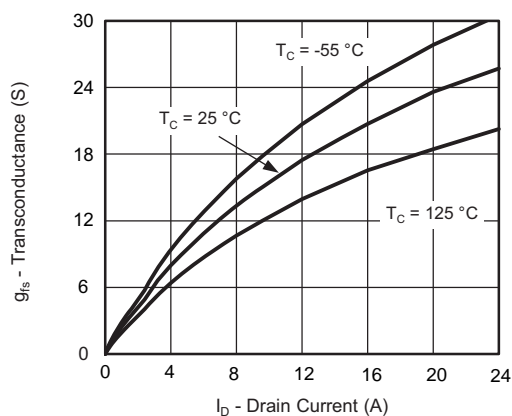
TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



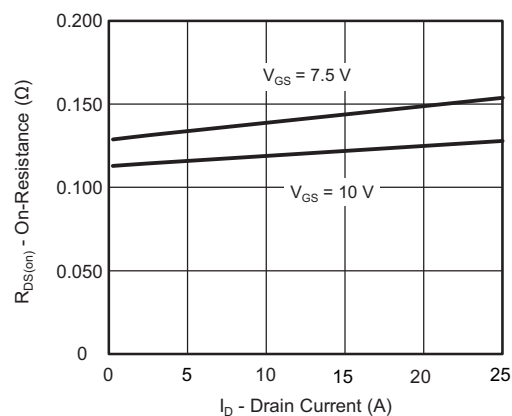
Output Characteristics



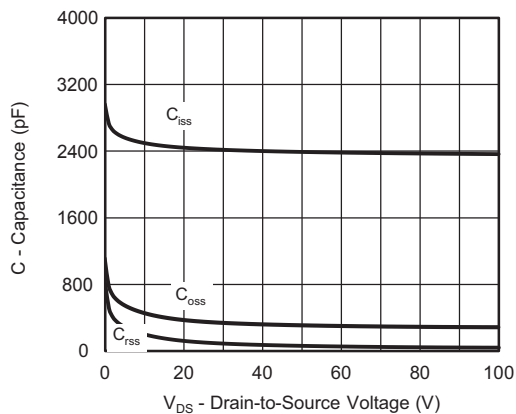
Transfer Characteristics



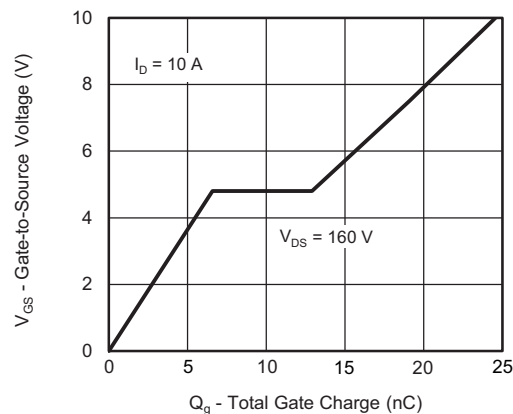
Transconductance



On-Resistance vs. Drain Current

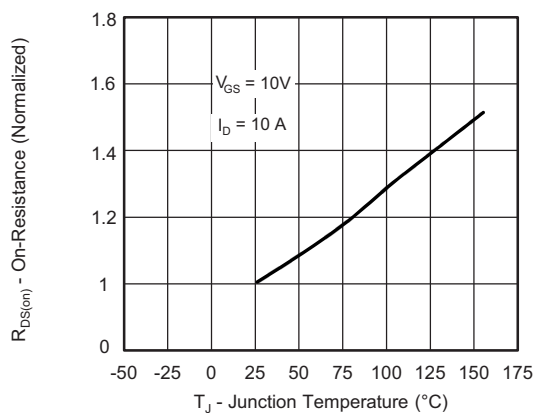


Capacitance

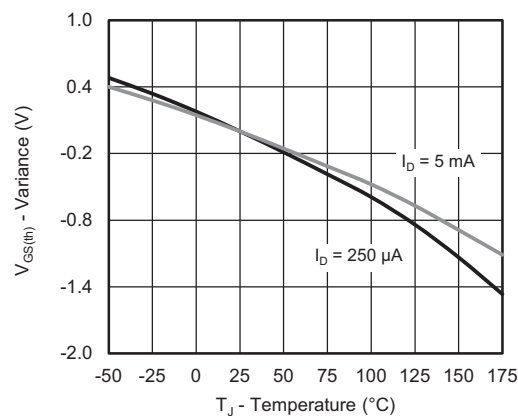


Gate Charge

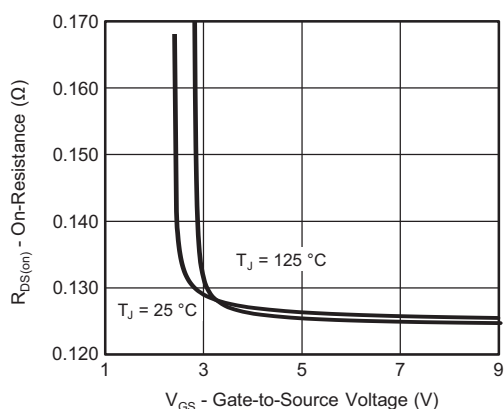
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



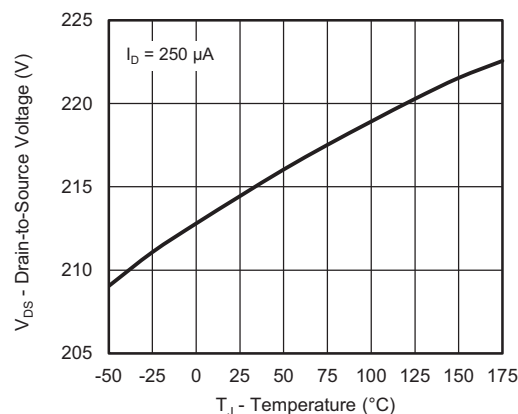
On-Resistance vs. Junction Temperature



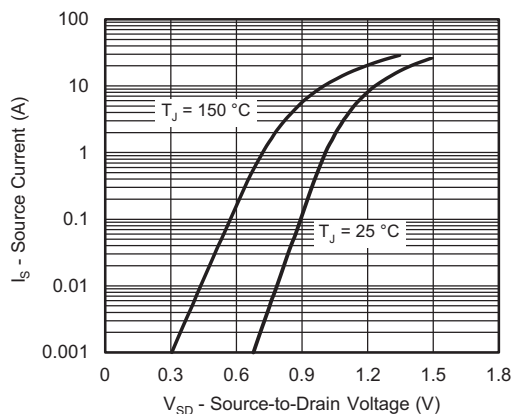
Threshold Voltage



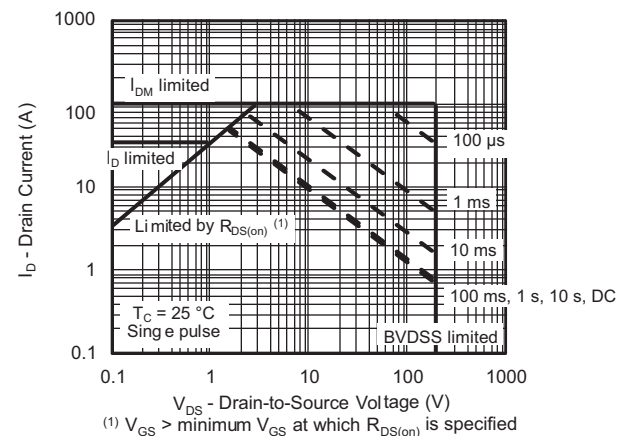
On-Resistance vs. Gate-to-Source Voltage



Drain Source Breakdown vs. Junction Temperature



Source Drain Diode Forward Voltage



Safe Operating Area

THERMAL RATINGS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

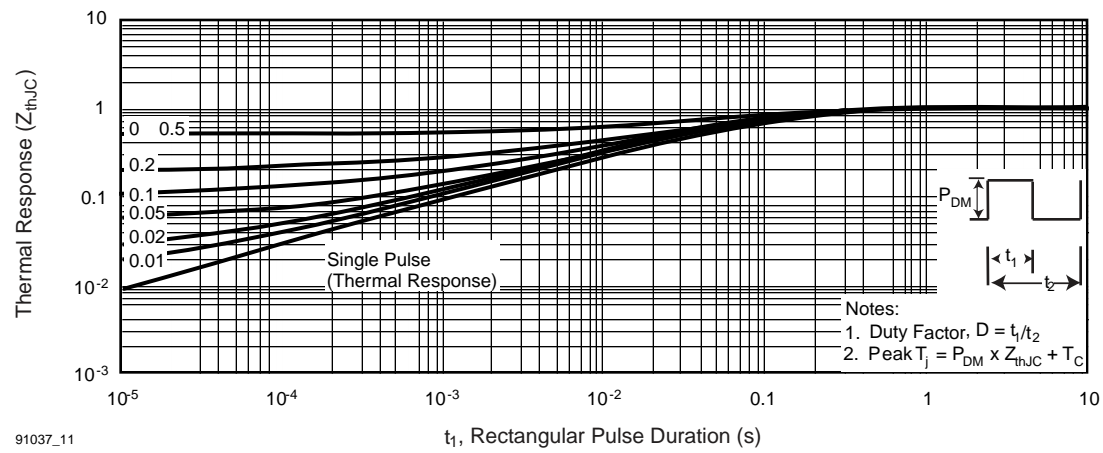


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

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